



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN181803

Date: May 01, 2018

Subject: Qualification of EME-G660B Mold Compound and Marketing Part Number Change for Select MM MCU Products at J-Devices

To:

Change Type: Major

Description of Change:

Cypress announces the qualification of EME-G660B mold compound for LQFP packages for select Mass Market MicroController Unit (MM MCU) products assembled at J-Devices.

Motivation for these changes was described and pre-announced in Advance PCN 173705B.

The present PCN corresponds to group GR10-A in the summary table contained in APCN 173705B.

This mold compound is consistent with Cypress's drive to Green and Pb-free RoHS compliant packages. In addition, this Green and Pb-free EME-G660B mold compound is compatible with industry standard reflow temperatures for applicable package volume, thickness and lead finish.

Material	J-Devices Current BOM	J-Devices New BOM
Mold Compound	Hitachi Non JD Standard Epoxy CEL-9210H	Sumitomo JD Standard Epoxy EME-G660B
Leadframe	Cu-alloy	Cu-alloy
Die Attach Material	Hitachi EN4600B	Hitachi EN4600B
Bond Wire	20µm CuPdAu wire	20µm CuPdAu wire

In addition, the marketing part numbers will change from the MB prefix to the CY prefix.

There may be some parts in GR10-A which will receive the mold compound change, but will not receive the SMIC Fab qualification; these parts will receive the SMIC Fab qualification in GR10-B. By the time the PCN for GR10-B is issued, all three changes will have been qualified for all 17 parts comprising that group.

Benefit of Change:

The qualification of the standard J-Devices mold compound allows for an improvement in product reliability and product cycle time.

Part Numbers Affected: 17

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:

The change has been qualified through a series of tests documented in Qualification Test Plans QTP#173409 and QTP#173410. The qualification reports can be found as attachments to this notification or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Sample Status:

Qualification samples may not be built ahead of time for all part numbers affected by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated J-Devices Fukuoka and J-Devices Usuki sample ordering part numbers. Samples are available now unless there is an indication that the sample ordering part numbers are subject to lead times. If you require qualification samples, please contact your local Cypress sales representative as soon as possible, but no later than 30 days from the date of this PCN, to place any sample orders.

Approximate Implementation Date:

The sample requests will be available as of the date of this notification. The MB part numbers listed in attached file will be supported according to the Last Time Buy (LTB) and Last Time Ship (LTS) dates provided. Your Cypress Sales rep will be in touch with you during the LTB phase to manage the backlog transition from MB marketing part number to CY marketing part number, depending on inventory depletion level.

Anticipated Impact:

Products assembled are completely compatible with existing products from form, fit, functional, parametric, and quality performance perspectives.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Item	Marketing Part Number	New Part Number	New Mold Compound	Cu Wire Change	Package Code	Last Time Buy (LTB) Date	Last Time Ship (LTS) Date
1	MB9BF116SPMC-GK7E1	CY9BF116SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
2	MB9BF129SPMC-GK7E1	CY9BF129SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
3	MB9BF216SPMC-GE1	CY9BF216SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
4	MB9BF218SPMC-GK7E1	CY9BF218SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
5	MB9BF218TPMC-GK7E1	CY9BF218TPMC-GK7E1	Mold	N/A	LQP176	31-Oct-18	29-Apr-19
6	MB9BF316SPMC-GE1	CY9BF316SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
7	MB9BF318SPMC-GK7E1	CY9BF318SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
8	MB9BF318TPMC-GE1	CY9BF318TPMC-GK7E1	Mold	N/A	LQP176	31-Oct-18	29-Apr-19
9	MB9BF328SPMC-GE1	CY9BF328SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
10	MB9BF416SPMC-GE1	CY9BF416SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
11	MB9BF429SPMC-GK7E1	CY9BF429SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
12	MB9BF517SPMC-GK7E1	CY9BF517SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
13	MB9BF518SPMC-GK7E1	CY9BF518SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
14	MB9BF518TPMC-GE1	CY9BF518TPMC-GK7E1	Mold	N/A	LQP176	31-Oct-18	29-Apr-19
15	MB9BF529TPMC-GE1	CY9BF529TPMC-GK7E1	Mold	N/A	LQP176	31-Oct-18	29-Apr-19
16	MB9BF618SPMC-GK7E1	CY9BF618SPMC-GK7E1	Mold	N/A	LQS144	31-Oct-18	29-Apr-19
17	MB9BF618TPMC-GK7E1	CY9BF618TPMC-GK7E1	Mold	N/A	LQP176	31-Oct-18	29-Apr-19